Dynastrip™ DL7630
• Removes photoresist and post-etch residue from dry metal etch processes
• Dissolves negative photoresist in solder bumping processes
• For use in single-wafer clean processes

Dynastrip™ DL88
• Formulated to strip positive photoresist from metals that are sensitive to corrosion
• Dynastrip DL88 is completely water rinsable.
• Effective for flux residue removal
• Batch spray processing

Dynastrip™ DL800
• Designed to strip positive photoresist
• Exceptionally low metal etch rates
• Contains no NMP, DMSO, TMAH, or hydroxylamine

Dynastrip™ DL8800
• Cutting-edge technology for thick dry film or liquid photoresist and post-etch residue removal
• Improved EN&F footprint; formulation contains no hydroxylamine or tetramethyl ammonium hydroxide (TMAH); outstanding cleaning and metal compatibility while raising the bar for environmental, health, and safety compliance

Dynastrip™ DL9150
• Cutting-edge technology for thick dry film or liquid photoresist and post-etch residue removal
• Improved EN&F footprint; formulation contains no hydroxylamine or tetramethyl ammonium hydroxide (TMAH); outstanding cleaning and metal compatibility while raising the bar for environmental, health, and safety compliance

FlipStrip™
• For removal of negative dry-film photoresists that are difficult to remove due to high-temperature reflow process
• Compatible with Cu, Al, and most polyimide (PI)
• Very high loading capacity of photoresist
• Greater than a 72-hour bath life

Dynasolve 219
• For removal of temporary adhesive materials in applications where a better penetrating solvent is required due to a smaller exposed surface area
• Quick dissolution of silicone-based adhesives

Dynasolve FS820
• Designed specifically for removing flux after solder reflow process
• Grains resist, no-clean, and water soluble flux

Dynasolve PI4310
• Prowen solution for removal or rework of PI dielectric layers
• Removes PI through various process stages from coat through post-develop bake process

EH&S (environmental, health, and safety) advantaged—product does not contain any of the following materials:
• Tetramethyl ammonium hydroxide (TMAH)
• Hydroxylamine (HA)
• Dimethylsulfoxide (DMSO)
• N-methylpyrrolidone (NMP)

Photosensitive and residue removers

Dynastrip™ DL9240
• Green technology for photoresist removal
• Improved EN&F footprint; formulation contains no DMSO and no hydroxylamine or tetramethyl ammonium hydroxide (TMAH); removes negative dry-film resist

Dynastrip™ DL9150B
• Cutting-edge technology for thick dry film or liquid photoresist and post-etch residue removal
• Improved EH&S footprint; formulation contains no hydroxylamine or tetramethyl ammonium hydroxide (TMAH); outstanding cleaning and metal compatibility while raising the bar for environmental, health, and safety compliance

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The family of Dynaloy products cleans a broad range of residue and photoresist from semiconductor wafers. Dynastrip products provide outstanding cleaning and surface preparation utilizing all current cleaning processes such as immersion, spray, and single-wafer.

Dynastrip™ 7000
- For removal of negative dry-film photoresists
- Cost-effective removal with high loading capacity
- Good heated solution lifetime stability
- Dynastrip™ 7000 is compatible with Cu, Ni, and Sn.

Dynastrip™ 7000T
- Cost-effective for removal of both negative dry-film photoresists and positive resists
- Excellent compatibility with most films layers
- Dynastrip™ 7000T is compatible with Cu, Ni, and Sn.

Dynastrip™ 7700 and Dynastrip™ 7700S
- Successful for dissolving hard to remove thick-negative photoresist in solder bumping processes, including lead-free processes
- Dynastrip™ 7700 is compatible with Cu, Ni, and Sn.

Dynastrip™ AP1010
- Dynaloy’s water-based removal technology, formulated for removal of thick photoresist in an immersion process
- Removes thick negative dry film or thick-positive or negative spin-on photoresist
- Dynastrip™ AP1010 is compatible with Cu, Ni, and Sn.

Dynastrip™ AP7880-C
- Proven and patented technology for dissolving hardest to remove thick-negative photoresist in solder bumping processes, including lead-free processes
- High loading capacity results in low process CoO
- Dynastrip™ AP7880-C is available in Asia Pacific market
- Dynastrip™ AP7880-NT available in North American market

Dynastrip™ AP7880-NA
- Proven and patented removal technology, formulated for removal of thick photoresist used in advanced packaging and Cu pillar processes
- Dynastrip™ AP7880-NA is available in North American market

Dynastrip™ AP7900A
- Formulated to strip thick photoresist in Cu pillar processes
- High loading capacity
- Long heated bath lifetime
- Dynastrip™ AP7900A is available in Asia Pacific market

Dynastrip™ AP7900C
- Formulated to strip thick photoresist in Cu pillar processes
- High loading capacity
- Long heated bath lifetime
- Dynastrip™ AP7900C is available in Asia Pacific market

Dynastrip™ DL3000
- Sticks cyclized negative photoresist that has been exposed and processed
- Dynastrip™ DL3000 is noncorrosive to most metals
- Contains no phenols or chlorinated hydrocarbons
- Dynastrip™ DL3000 is compatible with Cu, Ni, and Sn.


Photoresist and residue removers

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